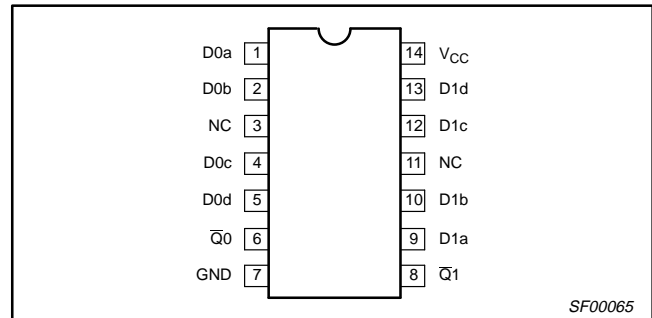


# Dual 4-input NAND buffer

# 74F40

TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F40	3.5ns	6mA

### PIN CONFIGURATION



### ORDERING INFORMATION

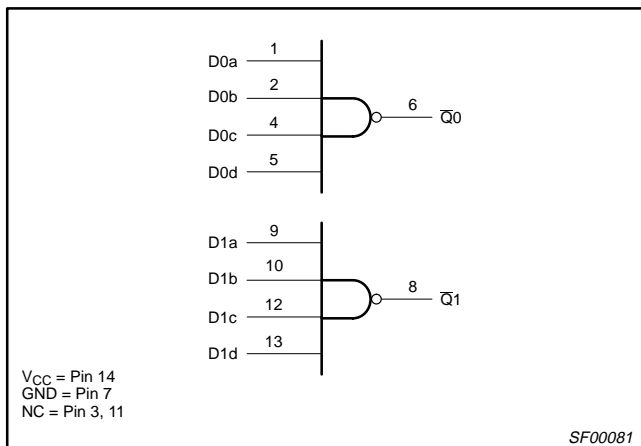
DESCRIPTION	COMMERCIAL RANGE $V_{CC} = 5V \pm 10\%$ , $T_{amb} = 0^{\circ}C$ to $+70^{\circ}C$
14-pin plastic DIP	N74F40N
14-pin plastic SO	N74F40D

### INPUT AND OUTPUT LOADING AND FAN OUT TABLE

PINS	DESCRIPTION	74F (U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
Dna, Dnb, Dnc, Dnd	Data inputs	1.0/2.0	20 $\mu$ A/1.2mA
$\bar{Q}0, \bar{Q}1$	Data outputs	750/106.7	15mA/64mA

**NOTE:** One (1.0) FAST unit load is defined as: 20 $\mu$ A in the High state and 0.6mA in the Low state.

### LOGIC DIAGRAM



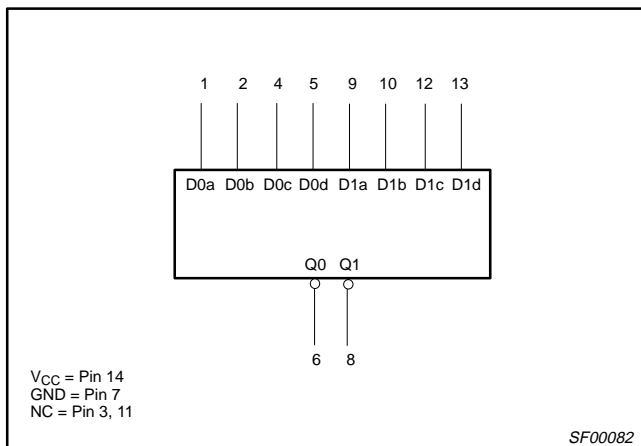
### FUNCTION TABLE

INPUTS				OUTPUT
Dna	Dnb	Dnc	Dnd	$\bar{Q}n$
L	X	X	X	H
X	L	X	X	H
X	X	L	X	H
X	X	X	X	H
H	H	H	H	L

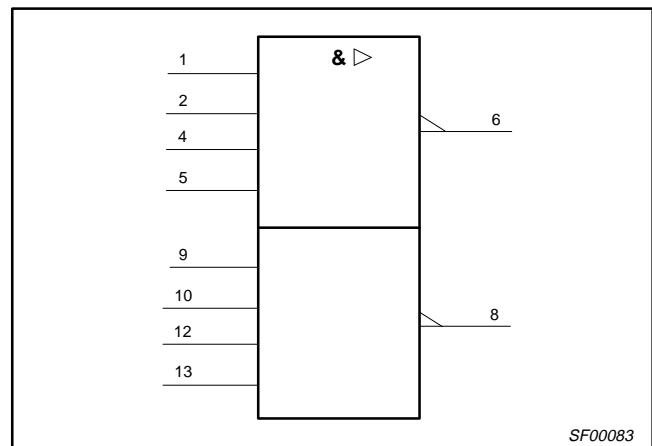
**NOTES:**

- H = High voltage level
- L = Low voltage level
- X = Don't care

### LOGIC SYMBOL



### IEC/IEEE SYMBOL



## Dual 4-input NAND buffer

74F40

**ABSOLUTE MAXIMUM RATINGS**

(Operation beyond the limits set forth in this table may impair the useful life of the device.  
Unless otherwise noted these limits are over the operating free-air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT
V <sub>CC</sub>	Supply voltage	-0.5 to +7.0	V
V <sub>IN</sub>	Input voltage	-0.5 to +7.0	V
I <sub>IN</sub>	Input current	-30 to +5	mA
V <sub>OUT</sub>	Voltage applied to output in High output state	-0.5 to V <sub>CC</sub>	V
I <sub>OUT</sub>	Current applied to output in Low output state	128	mA
T <sub>amb</sub>	Operating free-air temperature range	0 to +70	°C
T <sub>stg</sub>	Storage temperature range	-65 to +150	°C

**RECOMMENDED OPERATING CONDITIONS**

SYMBOL	PARAMETER	LIMITS			UNIT
		MIN	NOM	MAX	
V <sub>CC</sub>	Supply voltage	4.5	5.0	5.5	V
V <sub>IH</sub>	High-level input voltage	2.0			V
V <sub>IL</sub>	Low-level input voltage			0.8	V
I <sub>IK</sub>	Input clamp current			-18	mA
I <sub>OH</sub>	High-level output current			-15	mA
I <sub>OL</sub>	Low-level output current			64	mA
T <sub>amb</sub>	Operating free-air temperature range	0		+70	°C

**DC ELECTRICAL CHARACTERISTICS**

(Over recommended operating free-air temperature range unless otherwise noted.)

SYMBOL	PARAMETER	TEST CONDITIONS <sup>1</sup>	LIMITS			UNIT		
			MIN	TYP <sup>2</sup>	MAX			
V <sub>OH</sub>	High-level output voltage	V <sub>CC</sub> = MIN, V <sub>IL</sub> = MAX, V <sub>IH</sub> = MIN	I <sub>OH</sub> = -1mA	±10%V <sub>CC</sub>	2.5		V	
				±5%V <sub>CC</sub>	2.7	3.4		
			I <sub>OH</sub> = -15mA	±10%V <sub>CC</sub>	2.0		V	
				±5%V <sub>CC</sub>	2.0			
V <sub>OL</sub>	Low-level output voltage	V <sub>CC</sub> = MIN, V <sub>IL</sub> = MAX, V <sub>IH</sub> = MIN	I <sub>OL</sub> = MAX	±10%V <sub>CC</sub>		0.55	V	
				±5%V <sub>CC</sub>		0.42		0.55
V <sub>IK</sub>	Input clamp voltage	V <sub>CC</sub> = MIN, I <sub>I</sub> = I <sub>IK</sub>			-0.73	-1.2	V	
I <sub>I</sub>	Input current at maximum input voltage	V <sub>CC</sub> = MAX, V <sub>I</sub> = 7.0V				100	μA	
I <sub>IH</sub>	High-level input current	V <sub>CC</sub> = MAX, V <sub>I</sub> = 2.7V				20	μA	
I <sub>IL</sub>	Low-level input current	V <sub>CC</sub> = MAX, V <sub>I</sub> = 0.5V				-0.6	mA	
I <sub>OS</sub>	Short-circuit output current <sup>3</sup>	V <sub>CC</sub> = MAX			-100	-225	mA	
I <sub>CC</sub>	Supply current (total)	V <sub>CC</sub> = MAX		V <sub>IN</sub> = GND		1.75	4.0	mA
				V <sub>IN</sub> = 4.5V		11	17	

**NOTES:**

- For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
- All typical values are at V<sub>CC</sub> = 5V, T<sub>amb</sub> = 25°C.
- Not more than one output should be shorted at a time. For testing I<sub>OS</sub>, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a High output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I<sub>OS</sub> tests should be performed last.

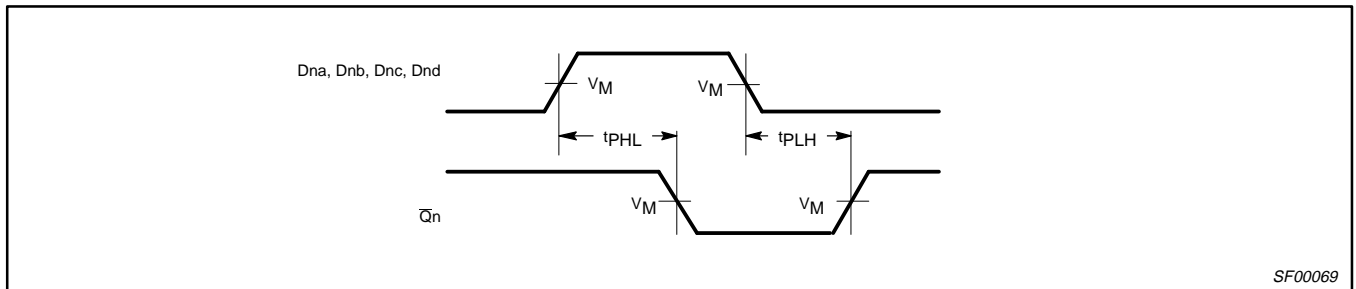
# Dual 4-input NAND buffer

74F40

## AC ELECTRICAL CHARACTERISTICS

SYMBOL	PARAMETER	TEST CONDITION	LIMITS					UNIT
			$V_{CC} = +5.0V$ $T_{amb} = +25^{\circ}C$ $C_L = 50pF, R_L = 500\Omega$			$V_{CC} = +5.0V \pm 10\%$ $T_{amb} = 0^{\circ}C \text{ to } +70^{\circ}C$ $C_L = 50pF, R_L = 500\Omega$		
			MIN	TYP	MAX	MIN	MAX	
$t_{PLH}$ $t_{PHL}$	Propagation delay Dna, Dnb, Dnc, Dnd to $\bar{Q}_n$	Waveform 1	2.0 1.5	4.0 3.0	6.0 5.0	1.5 1.0	7.0 5.5	ns

## AC WAVEFORMS



Waveform 1. Propagation Delay for Inverting Outputs

**NOTE:**

For all waveforms,  $V_M = 1.5V$ .

## TEST CIRCUIT AND WAVEFORMS

**Test Circuit for Totem-Pole Outputs**

**DEFINITIONS:**  
 $R_L$  = Load resistor; see AC electrical characteristics for value.  
 $C_L$  = Load capacitance includes jig and probe capacitance; see AC electrical characteristics for value.  
 $R_T$  = Termination resistance should be equal to  $Z_{OUT}$  of pulse generators.

**Input Pulse Definition**

family	INPUT PULSE REQUIREMENTS					
	amplitude	$V_M$	rep. rate	$t_w$	$t_{TLH}$	$t_{THL}$
74F	3.0V	1.5V	1MHz	500ns	2.5ns	2.5ns